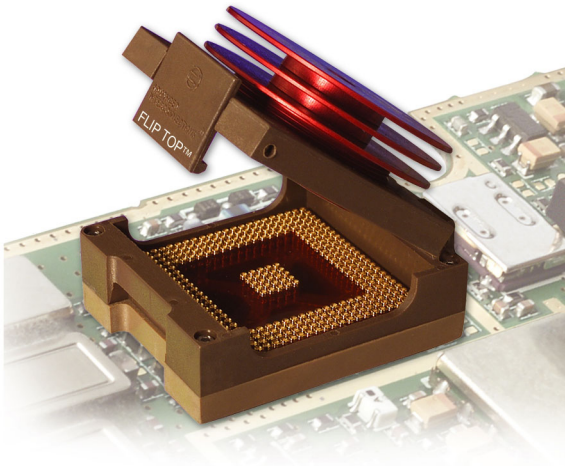


1.00mm Pitch Thru-hole Flip-Top™ BGA Socket



Usage Instructions

1. Place BGA device into opened Flip-Top™ Socket, aligning the A1 position on the BGA with the chamfered corner of the Flip-Top Socket.
2. Insert support plate with the recessed side (if applicable) toward the BGA device.
3. Close lid, making sure latch is firmly engaged.
4. Tighten heat sink or coin screw in a clockwise direction until it just makes contact with the support plate.
5. Turn the heat sink or coin screw an additional half turn. **Over tightening of heat sink or coin screw may result in product damage.**
6. Socket is now ready for operation.

BGA DEVICE REMOVAL

1. Loosen heat sink or coin screw until support plate moves freely. **To avoid damage to the socket, do not attempt to open the lid until heat sink or coin screw has been loosened.**
2. Press latch mechanism.
3. After lid is opened, remove the support plate and set aside.
4. Remove BGA device.

Installation

Socket to Board Application

Align and place the Flip-Top™ BGA Socket onto PC board using the chamfer as A1 pin location (see Fig. 1).

Reflow to PC Board (see Fig. 1a).

Open lid by pressing upper portion of latch mechanism back toward socket (see Fig. 3a below).

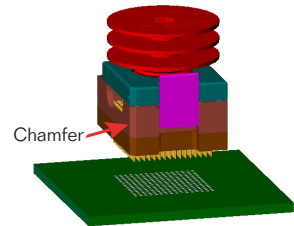


Fig.1 (Thru-hole PCB)

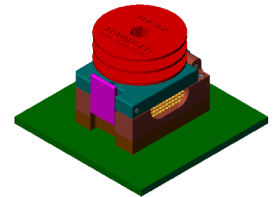


Fig.1a (After reflow)

Socket to Socket Application

Align and place the Flip-Top BGA Socket onto mating socket using the chamfer as A1 pin location (see Fig. 2).

Insert into socket (see Fig. 2a).

See Fig. 3 for assembled view.

Open lid by pressing upper portion of latch mechanism back toward socket (see Fig. 3a).

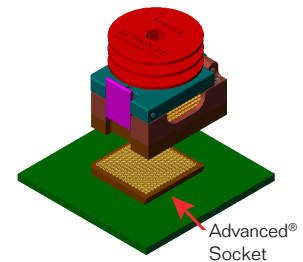


Fig.2 (Thru-hole or SMT PC Board)

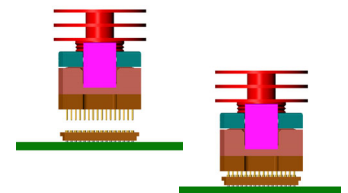


Fig.2a

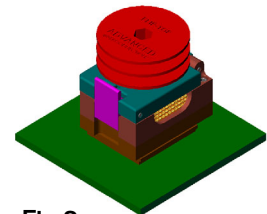


Fig.3

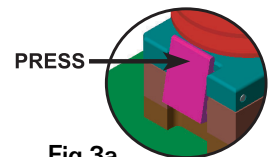


Fig.3a



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